



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of : Confirmation No. 5431  
Junichiro YOSHIOKA et al. : Docket No. 2001-0322A  
Serial No. 09/809,295 : Group Art Unit 1741  
Filed March 16, 2001 :

PLATING APPARATUS AND METHOD

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MAY 20 2002  
TC 1700

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,  
Washington, D.C.

Sir:

Prior to action on the above-referenced U.S. patent application, kindly amend the application as follows:

IN THE CLAIMS

Please amend the claims as follows:

21. (Amended) a plating apparatus for forming a protruding electrode on a substrate having wiring formed thereon, comprising:

a cassette table for loading a cassette housing the substrate therein;

a plating tank for plating the substrate;

a cleaning unit for cleaning the plated substrate;

a drying unit for drying the cleaned substrate;

a deaerating unit for deaerating a plating liquid;

a plating liquid regulating unit for analyzing the components of the plating liquid and adding components to the plating liquid based on the results of the analysis; and

a substrate transferring device for transferring the substrate.